

AMENDMENTS

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) An electric communication signal block resonator, comprising:
a block of dielectric materials having an outside surface including a top surface, a bottom surface, and at least first and second side surfaces; said block defining a plurality of through-holes, each through-hole extending from an opening in said bottom surface to an opening in said top surface; and
a metallization deposited via a photodefinable process onto said block, wherein said metallization includes varactor mounting pads attaching tunable varactors by using mask patterns for coupling lines and said varactors mounting pads.
2. (Original) The electric communication signal block resonator of claim 1, wherein said metallization includes input/output coupling metallization deposited via a photodefinable process.
3. Cancelled.
4. (Original) The electric communication signal block resonator of claim 1, further comprising:
at least one additional block of dielectric materials having an outside surface including a top surface, a bottom surface, and at least first and second side surfaces;
said at least one additional block defining a plurality of through-holes, each through-hole extending from an opening in said bottom surface to an opening in said top surface;
a metallization deposited via a photodefinable process onto said at least one additional block; and

said block of dielectric material and said at least one additional block of dielectric material are connected via an iris between said block of dielectric material and said at least one additional block of dielectric material.

5. (Currently Amended) An RF filter, comprising:

a block of dielectric material;

said block of dielectric material having an electrode pattern that adheres to at least one surface of said block; and

said electrode pattern consisting of a photodefinable metallization covering at least one surface of said block of dielectric material ~~converted to a photodefined patterned metallization on at least one surface of said dielectric material~~, wherein said metallization includes varactor mounting pads to incorporate tunable varactors via said photodefinable process.

6. (Currently Amended) The RF filter of claim 5, wherein said electrode pattern consisting of a photodefinable metallization covering at least one surface of said block of dielectric material ~~converted to a photodefined patterned metallization on at least one surface of said dielectric material~~ is an electrode pattern consisting of a photodefinable metallization covering all surfaces of said block of dielectric material ~~converted to a photodefined patterned metallization on from one to all surfaces of said dielectric material~~.

7. (Currently Amended) The RF filter of claim 5, wherein said photodefinable metallization covering at least one surface of said block of dielectric material ~~metallization~~ includes input/output coupling metallization deposited via a photodefinable process.

8. (Currently Amended) The RF filter of claim 5, wherein said photodefinable metallization covering at least one surface of said block of dielectric material ~~metallization~~ includes metallization of tunable varactors deposited via a photodefinable process.

9. (Currently Amended) The RF filter of claim 5, further comprising:
at least one additional block of dielectric material;
said at least one additional block of dielectric material having an electrode pattern that adheres to at least one surface of said block;
said electrode pattern consisting of a photodefinable metallization covering at least one surface of said at least one additional block of dielectric material ~~converted to a photodefined patterned metallization on at least one surface of said dielectric material of said at least one additional block~~; and
said block of dielectric material and said at least one additional block of dielectric material are connected via an iris between said block of dielectric material and said at least one additional block of dielectric material.
10. (Currently Amended) An electronic communication block, comprising:
a block of dielectric material;
said block of dielectric material having an electrode pattern that adheres to at least one surface of said block that is less than 4mm square; and
said electrode pattern consisting of a photodefinable metallization covering at least one surface of said block of dielectric material ~~converted to a photodefined patterned metallization on at least one surface of said dielectric material~~, wherein said metallization includes varactor mounting pads to incorporate tunable varactors via said photodefinable process.
11. (Currently Amended) The electric communication signal block resonator of claim 1, further comprising wherein at least one of said photodefined metallic patterned surfaces are less than 4mm square.
12. (Cancelled)
13. (Cancelled)

14. (Cancelled)

15. (Cancelled)

16. (Cancelled)

17. (Cancelled)

18. (Cancelled)

19. (Cancelled)

20. (Cancelled)

21. (Cancelled)

22. (Cancelled)